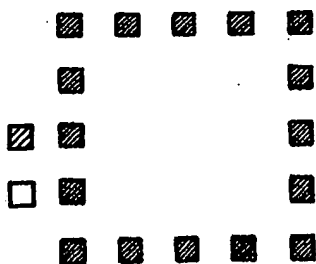


HIGH DENSITY INTEGRATED CIRCUITS AND THE METHOD  
OF PACKAGING THE SAME

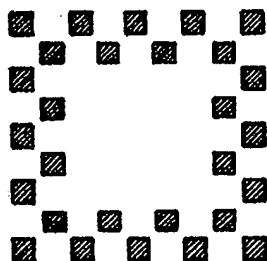
Inventor: Daniel Wang.

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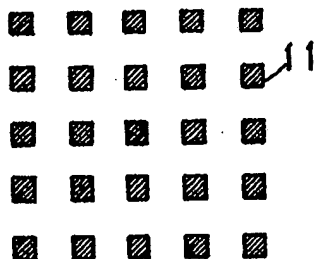
PRIOR ART

*Fig. 1.*  
PERIMETER I/O

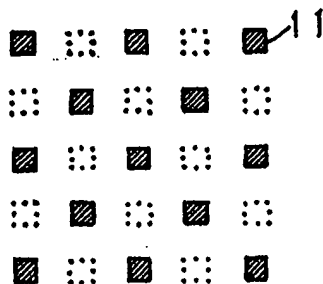


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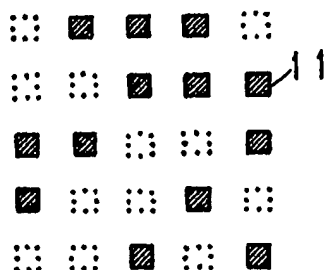
*Fig. 2.*  
STAGGERED PERIMETER I/O



*Fig. 3.*  
FULL ARRAY



*Fig. 4.*  
DEPOPULATED ARRAY



*Fig. 5.*  
RANDOM ARRAY

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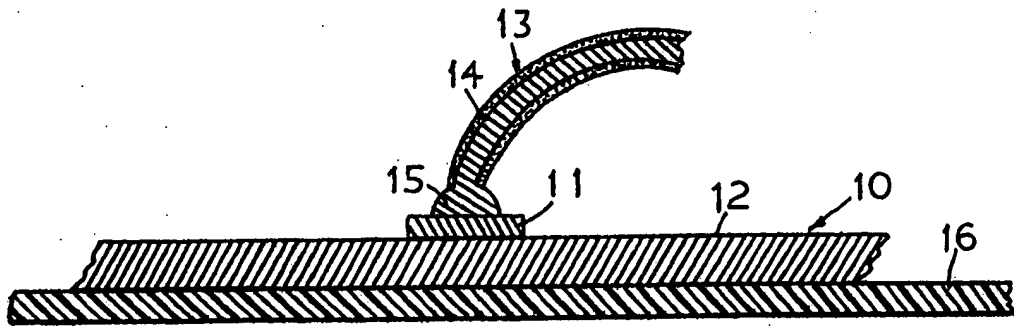


Fig. 6.

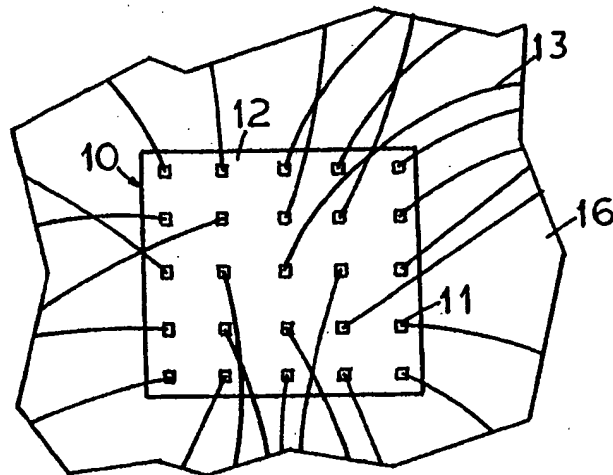


Fig. 7.

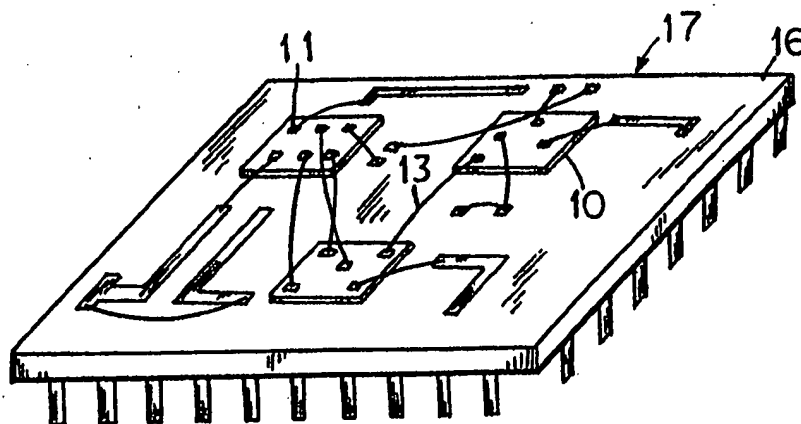


Fig. 8.

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